

# 412R Post-CMP Cleaner



The G&P Technology 412R post-CMP cleaning tool is a compact design that delivers state-of-the-art cleaning for 100mm to 300mm diameter substrates. Ideally suited for development applications, the 412R includes two double-side PVA brush stations, a drying station, and optional megasonic cleaning.

## FEATURES

- 100mm to 300mm wafer size
- 2 double-sided PVA brush stations
- Single wafer load rinse station
- Spin rinse dry output station

## Options

- Megasonic Unit for enhanced cleaning
- Quick dump rinse (QDR-1, single tank)
- Quick dump rinse (QDR-2, recycling)
- Cleaner gripper option

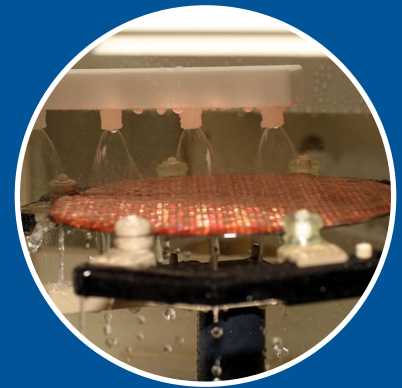


# 412R Post-CMP Cleaner

Spin Rinse Dry Output Station



Single Wafer Load Input Rinse Station



Spin Rinse Dry Output Station



STANDARD CONFIGURATION - Model 412R	
Wafer size capacity	100mm to 300mm
Cleaning sequence	Single wafer, Manual load
	Pre-cleaning DI H <sub>2</sub> O rinse
	1st double-sided PVA brush
	2nd double-sided PVA brush
	Spin rinse and dry (SRD)
Number of Brush Stations	2, double-sided PVA
Brush size	70 OD x 31 ID x 170 L
Rotating speed	30 – 200 rpm
Brush position adjustment angle	± 5°
Number of chemical inputs	2
Type (typical)	NH <sub>4</sub> OH or DI H <sub>2</sub> O
Chemical supply	4 spray nozzles and through the brush
Spin Station rotational speed	Up to 2500 rpm
Spin station rinse	DI H <sub>2</sub> O
Blow off/Drying method	N <sub>2</sub> blow off
Process	Single wafer manual load
Operator interface	Intuitive touch screen
Cleaning time (typical)	3-5 minutes per wafer

OPTIONS AVAILABLE	
Megasonic Unit	For enhanced cleaning action
Quick Dump Rinse (QDR-1)	Simple tank type
Quick Dump Rinse (QDR-2)	Recycling type
Cleaner Gripper option	4, 6, 8, 12 inch

DIMENSIONS		
Metric	1290W x 1190D x 1540H	
Inches	51W x 47D x 61H	
Weight	500 kg	1102 lbs